

6th Generation CoolSiC™

650V SiC Schottky Diode

The CoolSiCTM generation 6 (G6) is the leading edge technology from Infineon for the SiC Schottky barrier diodes. The Infineon proprietary innovative G5 technology was enhanced in G6 by introducing further advancements like a novel Schottky metal system. The result is a family of products with improved efficiency over all load conditions, resulting from a lower figure of merit ($Q_c \times V_F$). The CoolSiCTM Schottky diode 650 V G6 has been designed to complement our 600 V and 650 V CoolMOSTM 7 families, meeting the most stringent application requirements in this voltage range.

Table 1 Key performance parameters

| · · · · · · · · · · · · · · · · · · · | | | | | |
|---|-------|------|--|--|--|
| Parameter | Value | Unit | | | |
| V_{RRM} | 650 | V | | | |
| $Q_{C} (V_{R} = 400 \text{ V})$ | 17.1 | nC | | | |
| $E_C (V_R = 400 \text{ V})$ | 3.2 | μЈ | | | |
| $I_F (T_C \le 140 ^{\circ}\text{C}, D = 1)$ | 12 | А | | | |
| $V_F (I_F = 12 \text{ A}, T_j = 25 \text{ °C})$ | 1.25 | V | | | |

Table 2 Package information

| Type / ordering Code | Package | Marking |
|----------------------|------------|---------|
| IDH12G65C6 | PG-TO220-2 | D1265C6 |

PG-TO220-2 CASE 1) Cathode 2) Anode 1 O O CASE

Features

- Best in class forward voltage (1.25 V)
- Best in class figure of merit $(Q_c \times V_F)$
- High dv/dt ruggedness (150 V/ns)

Benefits

- System efficiency improvement
- System cost and size savings due to the reduced cooling requirements
- Enabling higher frequency and increased power density

Potential Applications

- Power factor correction in SMPS
- Solar inverter
- Uninterruptible power supply

Product Validation

Qualified for industrial applications according to the relevant tests of JEDEC (J-STD20 and JESD22)



Please read the Important Notice and Warnings at the end of this document

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IDH12G65C6



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1 Maximum ratings

Table 3 Maximum ratings

| Damamatan | Complete | Values | | | 11:4:4 | | |
|--|-----------------------|--------|------|------|------------------|--|--|
| Parameter | Symbol | Min. | Тур. | Max. | Unit | Note/Test condition | |
| | - - - - - - | - | _ | 12 | | $T_C \le 140 ^{\circ}\text{C}, D = 1$ | |
| Continuous forward current | | - | _ | 15 | | $T_C \le 125 ^{\circ}\text{C}, D = 1$ | |
| | | - | - | 27 | | $T_C \le 25 ^{\circ}\text{C}, D = 1$ | |
| Surge-repetitive forward current, sine halfwave ¹ | $I_{F,RM}$ | _ | _ | 53 | A | $T_C = 25 ^{\circ}\text{C}, t_p = 10 \text{ms}$ | |
| Surge non-repetitive forward | | - | _ | 64 | | $T_C = 25 ^{\circ}\text{C}, t_p = 10 \text{ms}$ | |
| current, sine halfwave | $I_{F,SM}$ | - | _ | 51 | | $T_C = 150 ^{\circ}\text{C}, t_{\rho} = 10 \text{ms}$ | |
| Non-repetitive peak forward current | I _{F,max} | _ | - | 630 | | T_C = 25 °C, t_p = 10 μs | |
| :24 | (:2-1+ | - | _ | 21 | A2- | $T_C = 25$ °C, $t_p = 10$ ms | |
| i ² t value | ∫ i²dt | _ | _ | 13 | A ² s | $T_C = 150 ^{\circ}\text{C}, t_p = 10 \text{ms}$ | |
| Repetitive peak reverse voltage | V _{RRM} | - | _ | 650 | V | <i>T_c</i> = 25 °C | |
| Diode dv/dt ruggedness | dv/dt | _ | _ | 150 | V/ns | <i>V_R</i> = 0480 V | |
| Power dissipation | P _{tot} | _ | _ | 81 | W | $T_C = 25^{\circ}\text{C}, R_{thJC,max}$ | |
| Operating and storage temperature | T_j T_{stg} | -55 | - | 175 | °C | - | |
| Mounting torque | _ | _ | _ | 70 | Ncm | M3 screw | |

2 Thermal characteristics

Table 4 Thermal characteristics (PG-TO-220-2)

| Davamatav | Cymphol | | Values | | Unit | Note/Test condition |
|--|------------|------|--------|------|---------|---------------------------------------|
| Parameter | Symbol | Min. | Тур. | Max. | Unit | Note/Test condition |
| Thermal resistance, junction- case | R_{thJC} | _ | 1.1 | 1.9 | 12 /\AI | _ |
| Thermal resistance, junction- ambient | R_{thJA} | _ | _ | 62 | K/W | leaded |
| Soldering temperature, wavesoldering only allowed at leads | T_{sold} | - | - | 260 | °C | 1.6 mm (0.063 in.) from case for 10 s |

¹ The surge-repetitive forward current test was performed with 1000 pulses (half-wave rectified sine with the 10 ms period).

Final Datasheet

3 Rev. 2.0, 2017-05-23



3 Electrical characteristics

3.1 Static characteristics

 Table 5
 Static characteristics

| Parameter | Comple al | | Value | S | 11 | Note/Test condition |
|-----------------------|-----------|------|-------|------|------|---|
| | Symbol | Min. | Тур. | Max. | Unit | |
| DC blocking voltage | V_{DC} | 650 | _ | _ | | <i>T_j</i> = 25 °C |
| Diode forward voltage | 17 | - | 1.25 | 1.35 | ٧ | $I_F = 12 \text{ A}, T_j = 25 \text{ °C}$ |
| | V_F | - | 1.5 | _ | | $I_F = 12 \text{ A}, T_j = 150 \text{ °C}$ |
| Reverse current | | - | 1.2 | 40 | | V_R = 420 V, T_j = 25 °C |
| | I_R | _ | 40 | _ | μΑ | V_R = 420 V, T_j = 125 °C |
| | | _ | 92 | _ | | $V_R = 420 \text{ V}, T_j = 150 ^{\circ}\text{C}$ |

3.2 AC characteristics

Table 6 AC characteristics

| Davamatav | Complete | Values | | | l lmia | Nata/Task Can dikian |
|-------------------------|----------|--------|------|------|--------|---|
| Parameter | Symbol | Min. | Тур. | Max. | Unit | Note/Test Condition |
| Total capacitive charge | Q_c | - | 17.1 | _ | nC | V_R = 400 V, T_j = 150 °C, di/dt = 200 A/ μ s, $I_F \le I_{F,MAX}$ |
| | | - | 594 | - | pF | $V_R = 1 \text{ V, } f = 1 \text{ MHz,}$ $T_j = 25 \text{ °C}$ |
| Total Capacitance | С | _ | 35 | - | | $V_R = 300 \text{ V}, f = 1 \text{ MHz},$ $T_j = 25 \text{ °C}$ |
| | | - | 34 | _ | | V_R = 600 V, f = 1 MHz, T_j = 25 °C |



4 Diagrams

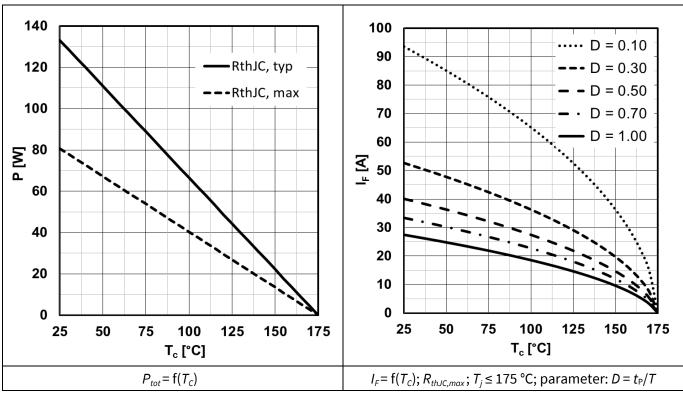


Figure 1 Power dissipation

Figure 2 Max. forward current

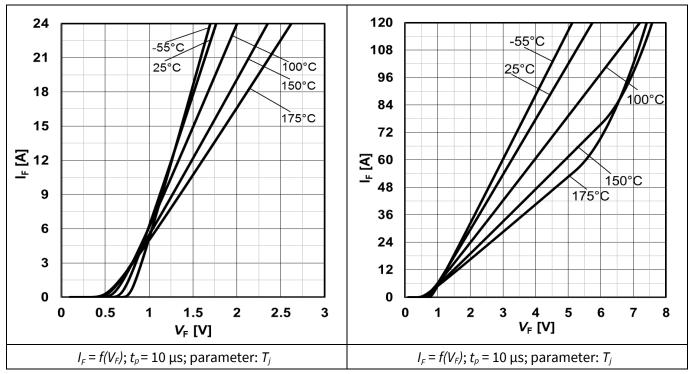


Figure 3 Typ. forward characteristics

Figure 4 Typ. forward characteristics in surge current



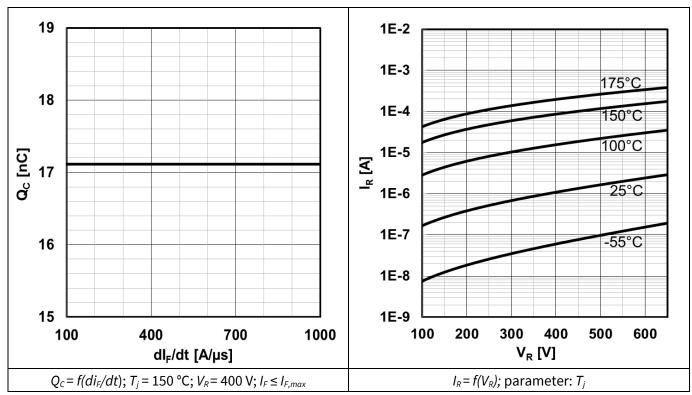


Figure 5 Typ. cap. charge vs. current slope

Figure 6 Typ. reverse current vs. reverse voltage

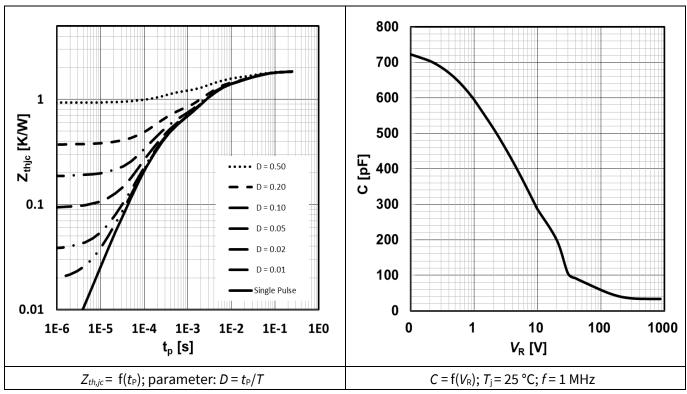


Figure 7 Max. transient thermal impedance

Figure 8 Typ. capacitance vs. reverse voltage



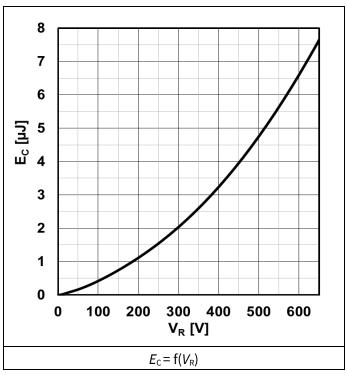


Figure 9 Typ. capacitance stored energy

5 Simplified forward characteristic

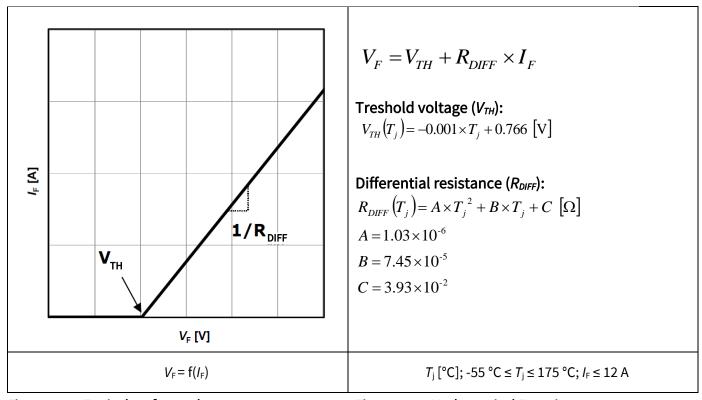


Figure 10 Equivalent forward current curve

Figure 11 Mathematical Equation



6 Package outlines

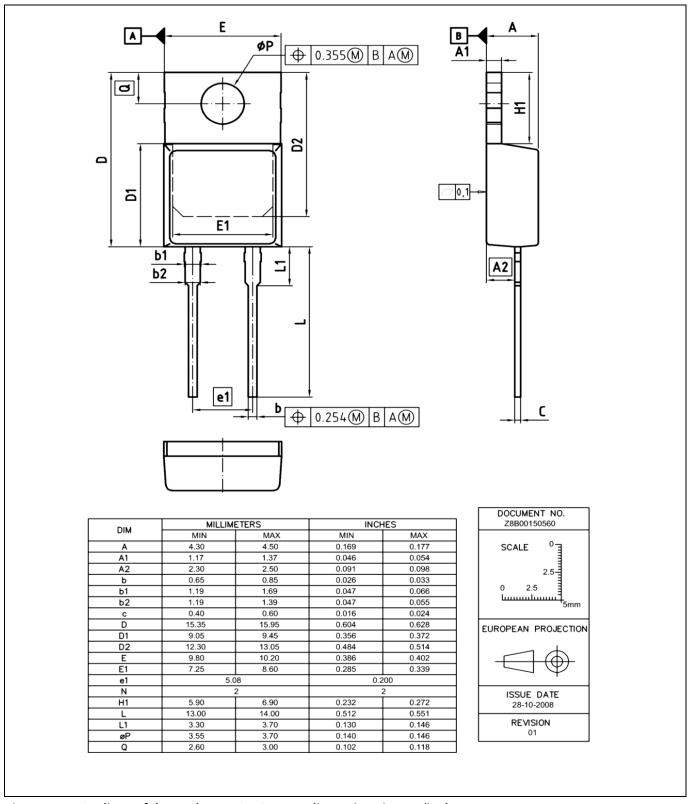


Figure 12 Outlines of the package PG-TO220-2, dimensions in mm/inches

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IDH12G65C6



Revision History

Major changes since the last revision

| Revision | Date | Subject (major changes since last revision) |
|----------|------------|---|
| 2.0 | 2017-05-23 | Release of final version |
| | | |
| | | |

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Document reference

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